Halogen-Free Product



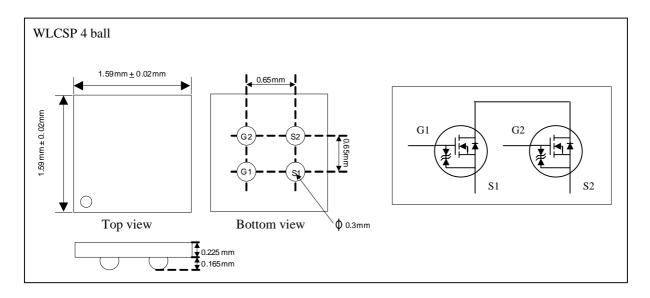
DUAL N-CHANNEL ENHANCEMENT
MODE POWER MOSFET

- **▼** Capable of 2.5V Gate Drive
- **▼** Ultra-small Package Outline
- **▼** Protection Diode Built-in
- **▼** RoHS Compliant & Halogen-Free

B _{SSS}	24V
R _{SS(ON)}	$\mathbf{22.5m}\Omega$
Is	9A

Description

AP2900 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for the load switch, charge switch, battery switch for portable application.



Absolute Maximum Ratings@T_i=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{SSS}		24	V
V_{GSS}		<u>+</u> 12	V
I _S	Source Current	9	Α
SM	Pulsed Source Current ¹	60	Α
P _D @T _A =25°ℂ	Total Power Dissipation ³	1.6	W
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}\!\mathbb{C}$
 Г _Ј	Junction Temperature	-55 to 150	$^{\circ}\!\mathbb{C}$

AP2900EC4



Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V(BR) _{SSS}	Source-Source Breakdown Voltage	V _{GS} =0V, I _S =1mA	24	-	-	V
R _{SS(ON)}	Static Source-Source On-Resistance ²	V _{GS} =4.5V, I _S =3A	15	18.8	22.5	$\mathbf{m}\Omega$
		V_{GS} =4V, I_S =3A	15.5	19.5	23	$\mathbf{m}\Omega$
		V_{GS} =3.7V, I_{S} =3A	16	20	24	$\mathbf{m}\Omega$
		V_{GS} =3.1V, I_{S} =3A	17	21.5	26	$\mathbf{m}\Omega$
		V_{GS} =2.5V, I_{S} =3A	20	24	30	$\mathbf{m}\Omega$
$V_{GS(off)}$	Cutoff Voltage	V _{SS} =10V, I _S =1mA	0.5	-	1.3	V
yfs	Forward Transfer Admittance	V_{SS} =10V, I_{S} =3A	-	30	-	S
I _{SSS}	Zero Gate Voltage Source Current	V _{SS} =20V, V _{GS} =0V	-	-	10	uA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=+8V$, $V_{SS}=0V$	-	-	<u>+</u> 30	uA
$t_{d(on)}$	Turn-on Delay Time	V _{SS} =10V	-	2	-	us
t _r	Rise Time	I _S =3A	-	4	-	us
$t_{d(off)}$	Turn-off Delay Time	V _{SS} =4.5V	-	18	-	us
t _f	Fall Time		-	9	-	us
Q_g	Total Gate Charge	V_{SS} =10V, V_{GS} =4.5V, I_{S} =3A	-	18	-	nC
$V_{F(S-S)}$	Forward Source-Source Voltage ²	$I_S=3A$, $V_{GS}=0V$	-	-	1.2	V

Notes:

- 1. Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3. Surface mounted on 1 in² 2oz copper pad of FR4 board, $t \le 10s$

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

When Ch-1 is measured, Gate and Source of Ch-2 are short-



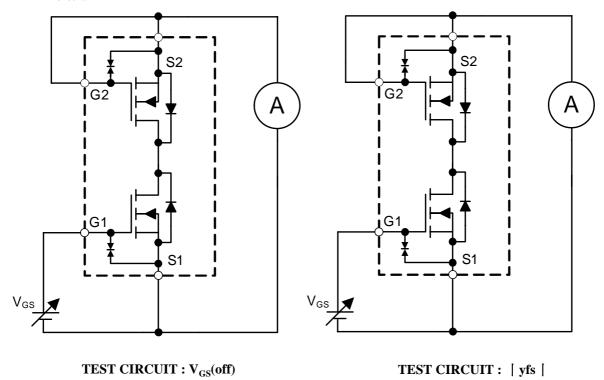
Test Circuits are Example of Measuring Channel-1 (unless otherwise specified)

S2 S2 G2 G1 G1

TEST CIRCUIT : I_{SSS} TEST CIRCUIT : I_{GSS}

When Ch-1 is measured, Gate and Source of Ch-2 are short-circuitd.

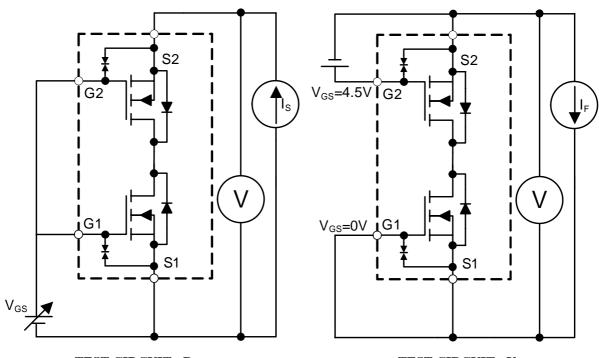
S1





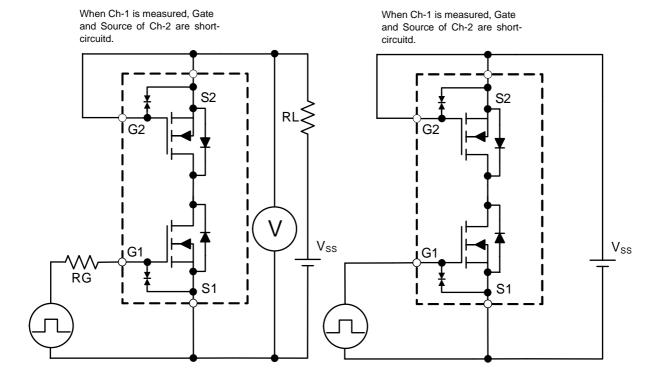
Test Circuits are Example of Measuring Channel-1 (unless otherwise specified)

When Ch-1 is measured, +4.5V is added to V_{GS} of Ch-2



TEST CIRCUIT: $R_{SS(ON)}$

TEST CIRCUIT: V_{F(S-S)}



TEST CIRCUIT: Switching Time

TEST CIRCUIT : Gate Charge



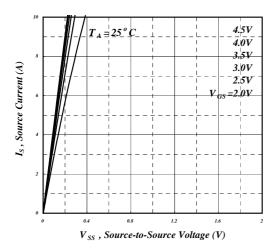
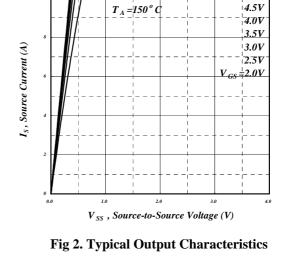


Fig 1. Typical Output Characteristics



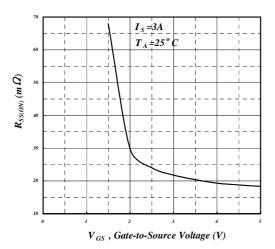


Fig 3. Static Source-to-Source On-Resistance v.s. Gate Voltage

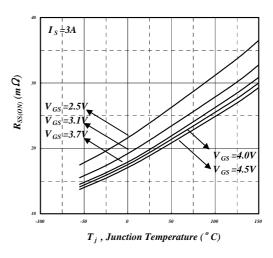


Fig 4. Typ. Source-to-Source on State Resistance v.s. Junction Temperature

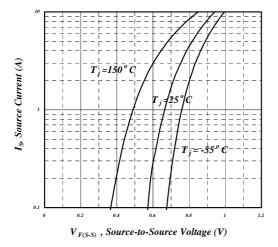


Fig 5. Forward Characteristic of Reverse Diode

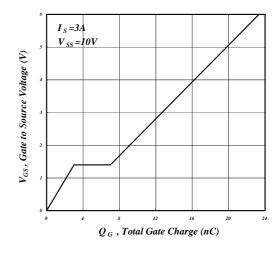


Fig 6. Gate Charge Characteristics



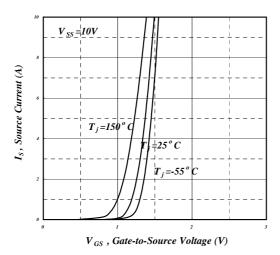
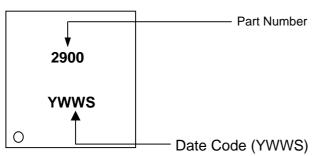


Fig 7. Transfer Characteristics



MARKING INFORMATION



Y: Last Digit Of The Year

WW: Week S: Sequence